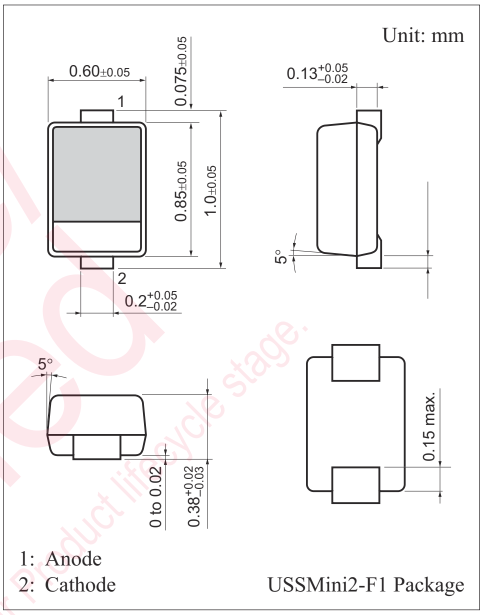
MAU2D29

Silicon epitaxial planar type

For high speed switching circuits



Marking Symbol: 1C

■ Features

- Optimum for high-density mounting
- Low forward voltage V_F
- Short reverse recovery time t_{rr}

■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	30	V
Repetitive peak reverse voltage	V_{RRM}	30	V
Forward current	I_F	100	mA
Peak forward current	I_{FM}	200	mA
Non-repetitive peak forward surge current *	I_{FSM}	1	A
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	−55 to +125	°C

Note) ∗: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

■ Electrical Characteristics $T_a = 25°C±3°C$

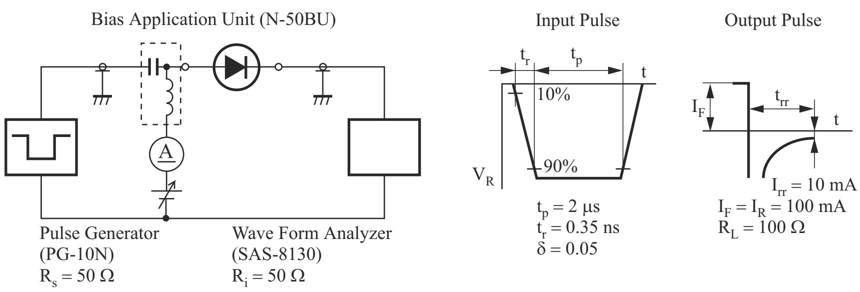
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_{F1}	$I_F = 10$ mA		0.25	0.29	V
	V_{F2}	$I_F = 100$ mA		0.39	0.42	V
Reverse current	I_{R1}	$V_R = 10$ V			25	μA
	I_{R2}	$V_R = 30$ V			120	μA
Terminal capacitance	C_t	$V_R = 0$ V, f = 1 MHz		11		pF
Reverse recovery time *	t_{rr}	$I_F = I_R = 100$ mA, $I_{rr} = 10$ mA, $R_L = 100\ \Omega$		1		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

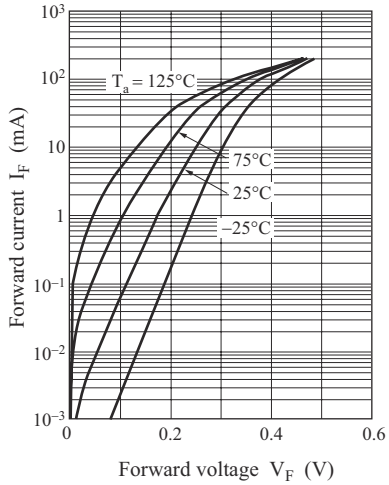
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. Absolute frequency of input and output is 250 MHz

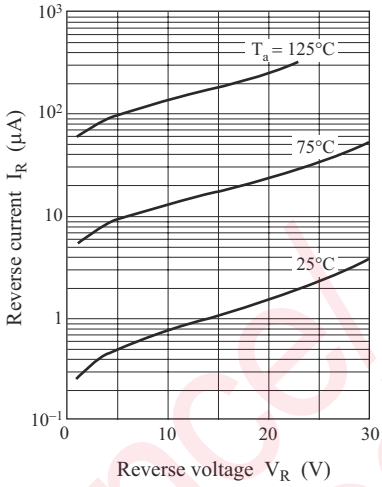
4. ∗: t_{rr} measurement circuit



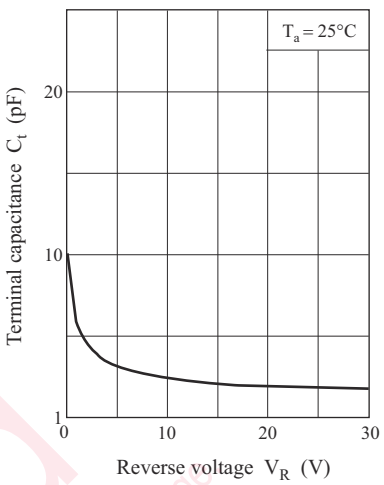
I_F — V_F



I_R — V_R



C_t — V_R



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